MOSFET – Power, N-Channel, SUPERFET III, FRFET 650 V, 20 A, 190 mΩ

NTPF190N65S3HF

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

Features

- $700 \text{ V} @ \text{T}_{\text{I}} = 150^{\circ}\text{C}$
- Typ. $R_{DS(on)} = 152 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 34 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 316 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

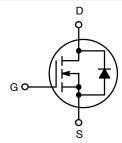
- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter



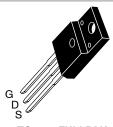
ON Semiconductor®

www.onsemi.com

V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	190 mΩ @ 10 V	20 A



POWER MOSFET



TO-220 FULLPAK CASE 221D

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code

NTPF190N65S3HF = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter	Value	Unit		
V_{DSS}	Drain to Source Voltage			V	
V_{GSS}	Gate to Source Voltage	- DC - AC (f > 1 Hz)		V	
I _D	Drain Current	– Continuous (T _C = 25°C)	20*	Α	
		- Continuous (T _C = 100°C)	12.7*	1	
I _{DM}	Drain Current	- Pulsed (Note 1)		Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	d Avalanche Energy (Note 2)		mJ	
I _{AS}	Avalanche Current (Note 2)	ne Current (Note 2)		Α	
E _{AR}	Repetitive Avalanche Energy (Note 1)	itive Avalanche Energy (Note 1)		mJ	
dv/dt	MOSFET dv/dt Peak Diode Recovery dv/dt (Note 3)		100	V/ns	
			50		
P_{D}	P_D Power Dissipation $(T_C = 25^{\circ}C)$		36	W	
		- Derate Above 25°C	0.29	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range	Operating and Storage Temperature Range		°C	
TL	Maximum Lead Temperature for Soldering, 1/8"	300	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
*Drain current limited by maximum junction temperature.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	3.5	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method Reel Siz		Tape Width	Quantity	
NTPF190N65S3HF	NTPF190N65S3HF	TO-220 FULLPACK	Tube	N/A	N/A	50 Units	

^{1.} Repetitive rating: pulse–width limited by maximum junction temperature. 2. $I_{AS} = 3.7 \text{ A}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$. 3. $I_{SD} \le 10 \text{ A}$, $di/dt \le 200 \text{ A/µs}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS		•			
BV _{DSS} Drain to Source Breakdown Voltage		$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$ 650				V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C		0.65		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V			10	μΑ
		V _{DS} = 520 V, T _C = 125°C		65		
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
ON CHARACTE	RISTICS		•			
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 0.43$ mA	3.0		5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 10 A		152	190	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 10 A		11		S
DYNAMIC CHA	RACTERISTICS					
C _{iss}	Input Capacitance	.,		1610		pF
C _{oss}	Output Capacitance	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		30		pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		316		pF
C _{oss(er.)}	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		59		pF
Q _{g(tot)}	Total Gate Charge at 10 V			34		nC
Q _{gs}	Gate to Source Gate Charge	$V_{DS} = 400 \text{ V}, I_{D} = 10 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 4)		11		nC
Q _{gd}	Gate to Drain "Miller" Charge	(1111)		13		nC
ESR	Equivalent Series Resistance	f = 1 MHz		6.8		Ω
SWITCHING CH	IARACTERISTICS					
t _{d(on)}	Turn-On Delay Time			19		ns
t _r	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 10 \text{ A},$		19		ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V, R}_{g} = 4.7 \Omega$ (Note 4)		58		ns
t _f	Turn-Off Fall Time			14		ns
SOURCE-DRAI	N DIODE CHARACTERISTICS					
Is	Maximum Continuous Source to Drain I	ntinuous Source to Drain Diode Forward Current			20	Α
I _{SM}	Maximum Pulsed Source to Drain Diode	ximum Pulsed Source to Drain Diode Forward Current			50	Α
V_{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 10 A			1.3	٧
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 10 A,		80		ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs		264		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS

100

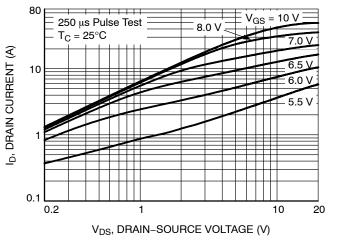


Figure 1. On-Region Characteristics

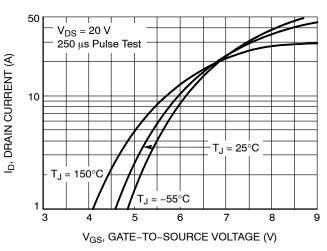


Figure 2. Transfer Characteristics

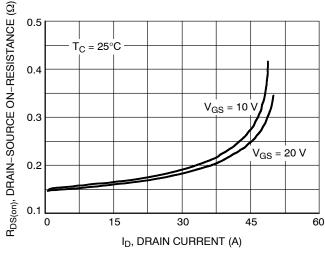
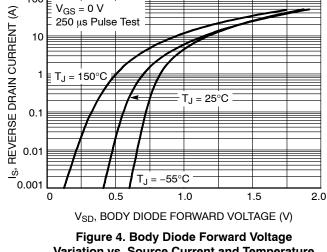


Figure 3. On-Resistance Variation vs. Drain **Current and Gate Voltage**



Variation vs. Source Current and Temperature

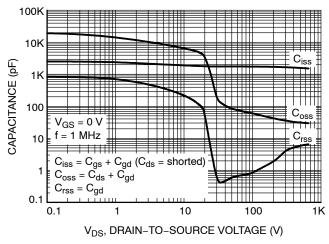


Figure 5. Capacitance Characteristics

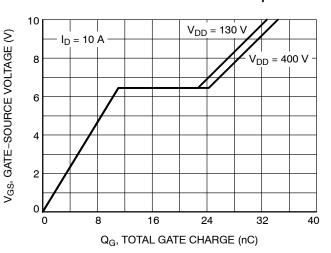


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS

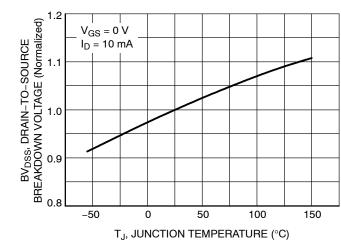


Figure 7. Breakdown Voltage Variation vs. Temperature

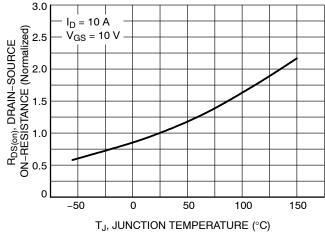


Figure 8. On-Resistance Variation vs.

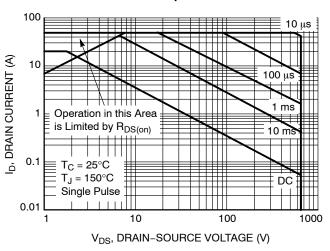


Figure 9. Maximum Safe Operating Area

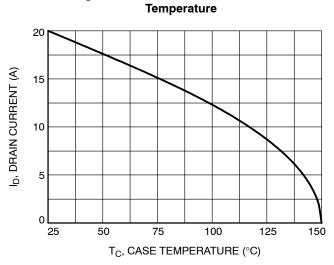


Figure 10. Maximum Drain Current vs. Case Temperature

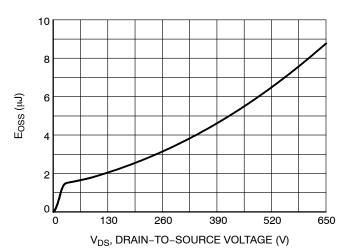


Figure 11. E_{OSS} vs. Drain-to-Source Voltage

TYPICAL CHARACTERISTICS

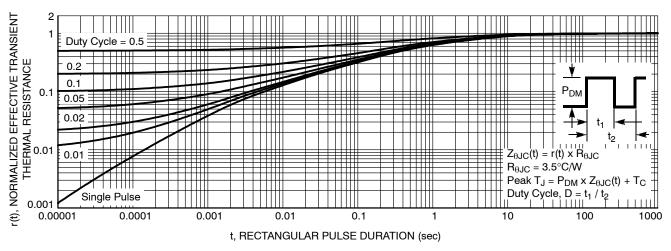


Figure 12. Transient Thermal Response Curve

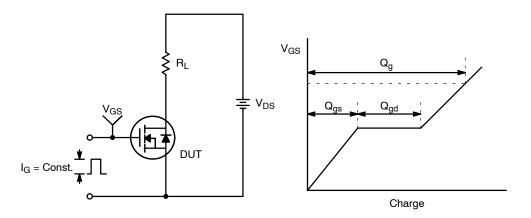


Figure 13. Gate Charge Test Circuit & Waveform

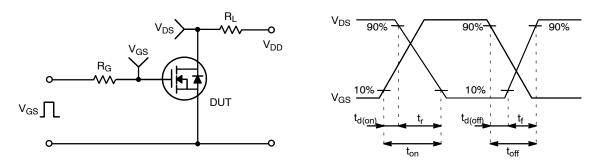


Figure 14. Resistive Switching Test Circuit & Waveforms

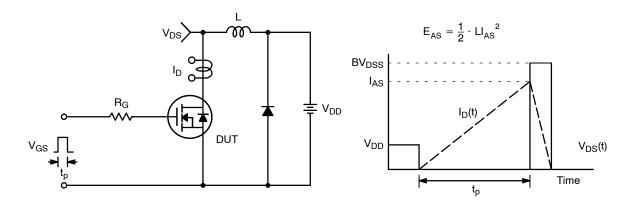


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

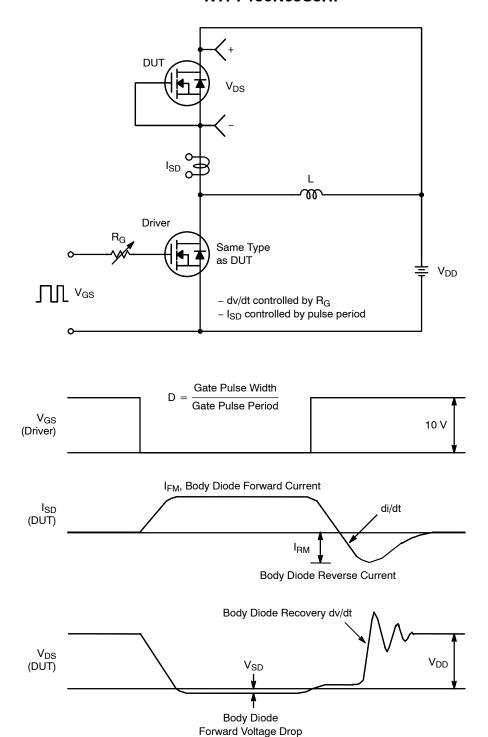


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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MECHANICAL CASE OUTLINE





SCALE 1:1

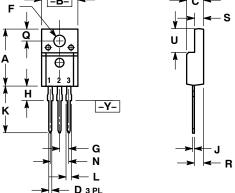
TO-220 FULLPAK CASE 221D-03 ISSUE K

DATE 27 FEB 2009

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

	INCHES		MILLIN	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.617	0.635	15.67	16.12	
В	0.392	0.419	9.96	10.63	
С	0.177	0.193	4.50	4.90	
D	0.024	0.039	0.60	1.00	
F	0.116	0.129	2.95	3.28	
G	0.100 BSC		2.54 BSC		
Н	0.118	0.135	3.00	3.43	
J	0.018	0.025	0.45	0.63	
K	0.503	0.541	12.78	13.73	
L	0.048	0.058	1.23	1.47	
N	0.200 BSC		5.08	BSC	
Q	0.122 0.1		3.10	3.50	
R	0.099	0.117	2.51	2.96	
S	0.092	0.113	2.34	2.87	
U	0.239	0.271	6.06	6.88	

-B-



| ⊕ | 0.25 (0.010) M | B M | Y

MARKING DIAGRAMS

STYLE 1: PIN 1. GATE 2. DRAIN 3. SOURCE

STYLE 4: PIN 1. CATHODE

3. CATHODE

ANODE

STYLE 2: PIN 1. BASE 2. COLLECTOR 3. EMITTER 2.

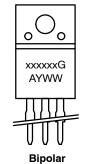
STYLE 5: PIN 1. CATHODE 2. ANODE 3. GATE

STYLE 6: PIN 1. MT 1 2. MT 2 3. GATE

STYLE 3: PIN 1. ANODE

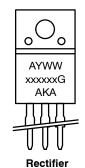
2. CATHODE

3. ANODE



xxxxxx = Specific Device Code = Pb-Free Package

Α = Assembly Location Υ = Year WW = Work Week



= Assembly Location

= Polarity Designator

Υ = Year = Work Week WW XXXXXX = Device Code = Pb-Free Package G

AKA

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